Dielectric constants of amorphous hafnium aluminates: First-principles study

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Amorphous model structures of hafnium aluminate having a Hf content of 0.2 (a-Hf_{0.2}Al_{0.8}O_{1.6}), alumina (a-Al₂O₃), and hafnia (a-HfO₂) are theoretically generated, and dielectric responses of the amorphous model structures are studied by the first-principles method. The models have corner, edge, and face shared AlO_n (n=4-6) and HfO_n (n=5-8) polyhedra, and the a-Hf_{0.2}Al_{0.8}O_{1.6} model structures are phase separated at the atomistic level, having Al₂O₃ and HfO₂ domains. Calculated dielectric constants of the models increase with increasing Hf content, and the dielectric constant increase is dominated by the lattice polarization contribution to the dielectric constant. We found that low-frequency phonon modes having a frequency less than 200 cm⁻¹ largely contribute to the high lattice dielectric constant and that inter-HfO₂ domain vibrations and vibration of atoms in distorted metal-oxygen polyhedra are dominant in the modes.

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I. INTRODUCTION

Recently, high-*k* materials (i.e., insulators having a higher dielectric constant than that of SiO₂ or SiON) have been investigated as the gate dielectrics of the next-generation complementary-metal-oxide-semiconductor (CMOS) transistor.^{1–3} Amorphous alumina (*a*-Al₂O₃), hafnia (*a*-HfO₂), and hafnium aluminates (*a*-Hf_xAl_{1-x}O_y) are thought to be promising candidate high-*k* materials.

Amorphous high-*k* materials have several advantages over crystalline high-*k* materials as the gate dielectrics; i.e., the amorphous materials have an isotropic dielectric constant and no crystalline domain boundary, which generally works as the path of leakage current through the materials, and can be processed by the conventional CMOS fabrication process. The more important feature of amorphous high-*k* materials is that their dielectric and electric properties, thermal stability, and the material/Si-substrate interfacial structure can be changed by controlling their chemical composition and/or by doping of other element atoms (e.g., N atoms).^{4–15}

Previous experimental studies have shown that the dielectric constants of a-Hf_xAl_{1-x}O_y increase from the a-Al₂O₃ values (8–11) to the a-HfO₂ values (15–25) with increasing Hf content (x), while the crystallization temperature of a-Hf_xAl_{1-x}O_y tends to decrease.^{4–6} The crystallization temperature, typically about 1000 °C, during the CMOS fabrication process.¹ Therefore the a-Hf_xAl_{1-x}O_y having a low x, e.g., 0.2–0.4, meets the requirements of the high-k gate dielectrics, showing better thermal stability than that of the a-HfO₂ and having a higher dielectric constant than that of the a-Al₂O₃.

In contrast to such experimental efforts, the structure and dielectric property of a-Hf_xAl_{1-x}O_y have not yet been theoretically understood at the atomistic level because of difficulties in treating amorphous materials by theoretical calculation. Previously, we studied the dielectric response of the a-Al₂O₃ at the atomistic level by constructing a-Al₂O₃

model structures using classical molecular-dynamics (MD) calculations and by calculating static dielectric constants of the model structures by first principles.^{16,17} We showed that the melt-and-quench MD calculation can generate a-Al₂O₃ model structures representing the experimental a-Al₂O₃ structure and that the dielectric response of a-Al₂O₃ can be studied by investigating the electronic as well as lattice dielectric constant was found to be dominant over the electronic one.

The aim of this study is to clarify structures and dielectric responses of a-Hf_xAl_{1-x}O_y with y=(3+x)/2 [i.e., a-(HfO₂)_x(AlO_{1.5})_{1-x} case] at the atomistic level, in a manner similar to that of our previous study. We theoretically generated model structures of a-HfO₂ and a-Hf_{0.2}Al_{0.8}O_{1.6}. Dielectric constants originating from electronic and lattice polarizations were calculated for these models by a first-principles method. We discuss dielectric responses of the a-Hf_{0.2}Al_{0.8}O_{1.6} (x=0.2) models in comparison with those of the a-HfO₂ (x=1) models and a previously studied a-Al₂O₃ (x=0) model.

Calculated dielectric constants of the a-HfO₂ and a-Hf_{0.2}Al_{0.8}O_{1.6} models are close to the corresponding experimental values, and the dielectric constant of the $a-Hf_{0.2}Al_{0.8}O_{1.6}$ models is in between those of the $a-HfO_2$ models and a-Al₂O₃ models. The results show that the dielectric constant of these amorphous models increases as the x increases, in accord with experiments. The increase is seen in both the electronic and lattice polarization contributions to the dielectric constant, and the increase in the lattice polarization contribution is more substantial. We found that the degree of the increase in lattice polarization differs between the a-Hf_xAl_{1-x}O_v models and that the degree significantly depends on their structure. It was found that $a-Hf_{0.2}Al_{0.8}O_{1.6}$ models are phase separated at the atomistic level into HfO₂ and Al₂O₃ domains, and that their high dielectric constant is dominated by elastic vibrational modes, causing interdomain vibrations and vibrations of atoms in distorted metal-oxygen polyhedra, with frequencies less than 200 cm⁻¹.

II. METHODS OF CALCULATIONS

model structures of $a-HfO_2$ Amorphous and a-Hf_{0.2}Al_{0.8}O_{1.6} were generated by classical MD calculations under the NPT ensemble using a time step of 1.0 fs.^{18-20} We used the empirical atom-atom pair potentials for metal oxides, which are parametrized by Matsui²¹ and Yamasaki et al.²² to reproduce experimental crystal structures and thermal properties of several metal oxides. The periodic boundary condition was used in the MD calculations, so that generated amorphous models have an unphysical translational periodicity. Previously, we examined the influence of such an unphysical translational periodicity on the dielectric constant of a-Al₂O₃ models by changing the unit-cell size.¹⁷ The dielectric tensor of amorphous materials should be isotropic and diagonal, and we obtained reasonable dielectric tensors for the 120 atoms/cell models (a-Al₄₈O₇₂, subscripts denote number of atoms in a unit cell) while quite anisotropic dielectric tensors for the 60 atoms/cell models. The result indicates that the use of a unit cell with the number of atoms at least about 100 atoms/cell is necessary. Thus, the number of atoms in the unit cell of 96 and 104 atoms/cell were used for a-HfO₂ models (a-Hf₃₂O₆₄) and a-Hf_{0.2}Al_{0.8}O_{1.6} models $(a-Hf_8Al_{32}O_{64})$, respectively.

The classical MD calculations were performed to obtain amorphous structures, using the melt-and-quench temperature control method as previously used for several oxides.^{17,22-27} Molten states were equilibrated at a temperature (3000-3200 K) higher than the melting point of Al₂O₃ and that of HfO₂, and then the system temperature was cooled down to 300 K linearly with time using a constant cooling rate. Finally, the systems were maintained for 4.0 ps at 300 K and equilibrated. We obtained model structures using several cooling rates. During the melt-and-quench MD calculations, the length of the unit cell was allowed to change under the zero pressure condition, while the unit-cell vectors were fixed to the right angle.

Models used in this study were generated as follows. Two a-Al₄₈O₇₂ were obtained using the cooling rates of 0.54 K/fs (model A) and 0.27 K/fs (model B) for the initial structure of the α -Al₂O₃ crystal. Two a-Hf₃₂O₆₄ were generated using the cooling rates of 1.35 K/fs (model A) and 0.54 K/fs (model B) for the initial structure of the cubic hafnia (*c*-HfO₂) crystal. Three a-Hf₈Al₃₂O₆₄ models were calculated using the cooling rate of 0.54 K/fs, and their initial structures were the modified a-Al₂O₃ such that Al-O atoms were replaced by Hf-O atoms (models A, B, and C). The distributions of eight Hf atoms in the initial structures were as spatially homogeneous as possible. Note that the Hf atoms in the a-Hf₈Al₃₂O₆₄ tend to cluster during the calculations even for the initial structures, as will be discussed in Sec. III.

To obtain the realistic amorphous models, the cooling rate was a crucial parameter in the melt-and-quench simulations. In the case of a-SiO₂, effects of the cooling rates on the structure have been investigated in a wide range, and reliable models can be obtained by the slow cooling rates (such as

 10^{13} K/s or slower).²⁸ Considering the *a*-SiO₂ case, it is necessary to choose a suitable range of the cooling rates also for the *a*-Hf_xAl_{1-x}O_y. For the slower cooling rates, however, the quenched structures of the a-Hf_xAl_{1-x}O_y systems showed stronger tendency to crystallize, e.g., the radial distribution function had periodic discrete peaks, especially for smaller systems containing fewer number of atoms in a unit cell. Actually, the HfO_2 is known as a reluctant glass former, whereas the SiO₂ is a well-known glass former. Even for the a-Al₂O₃, very fast cooling rates are necessary to obtain amorphous states in experiments.²⁹ Thus we used relatively faster cooling rates (0.27-1.35 K/fs) to obtain the amorphous structures. The calculated structures were compared with the experimental results to confirm the reliability of the models, as will be discussed in Sec. III. In the case of a-Al₂O₃, the calculated structures were in the experimental range.¹⁷ Note that the real films include vacancies, impurities, pores, nonstoichiometric composition, and so on. Their effects on the electrical and/or dielectric properties have been studied theoretically by using the crystals,^{14,15} though our amorphous models do not include them. In addition, the real a-Hf_xAl_{1-x}O_y have been prepared only in the thin-film states, usually by the deposition methods, and there is still a possibility that the films consist of microscopic crystals or phaseseparated domains, as will be discussed in Sec. III.

Obtained final classical MD structures of the amorphous models were optimized by the first-principles method; the optimization was continued until all atomic forces became less than 1.0 mRy/bohr, keeping the unit cell of the models and thus the density. First-principles calculations are based on the density-functional theory (DFT) within the local-density approximation (LDA) using the plane-wave pseudo-potential method.^{30–34} We used a plane-wave cutoff energy of 25 Ry for the Kohn-Sham wave functions and a sampling **k** point of the Γ for the structure optimizations.

Dielectric constants (ε) were calculated as a sum of the electronic and lattice polarization contributions (electronic and lattice dielectric constants, ε^{ele} and ε^{lat}) based on first principles,³⁴

$$\varepsilon = \varepsilon^{\text{ele}} + \varepsilon^{\text{lat}}.$$
 (1)

The dielectric constant of the high-*k* materials could be quantitatively estimated by calculating these two contributions separately. Previous studies have shown that the high-*k* materials have large $\varepsilon^{\text{lat},2,3,15-17,35-40}$ Note that the orientational averages of dielectric tensors are discussed in this paper. The ε^{ele} was calculated by considering direct interband electronic transitions from valence to conduction bands in the Brillouin zone, as described in the time-dependent perturbation theory of optical properties calculation.^{41,42} The imaginary part of ε^{ele} was calculated, and then the real part of ε^{ele} was obtained by the Kramers-Kronig relation. In this study, the ε^{ele} were calculated by using the sampling **k** points on the $2 \times 2 \times 2$ mesh and conduction bands up to about 50 eV above a valence-band top energy. The ε^{lat} is given as

$$\varepsilon^{\text{lat}} = \frac{4\pi e^2}{V} \sum_{\lambda} \left(\frac{Z_{\lambda}}{\omega_{\lambda}}\right)^2,\tag{2}$$

using phonon frequency ω_{λ} and mode effective charge Z_{λ} of a phonon mode λ . *V* is the volume of the unit cell. The ω_{λ}



FIG. 1. (Color online) Amorphous model structures of (a) a-Al₄₈O₇₂ (model A), (b) a-Hf₃₂O₆₄ (model A), and (c) a-Hf₈Al₃₂O₆₄ (models A, B, and C). Dark and bright shaded polyhedra show HfO_n and AlO_n polyhedra, respectively (*n* is the coordination number). The unit cell is shown by line boxes, and O atoms outside the unit cell neighboring to Al or Hf atoms inside the cell also are shown. The length of the unit cell is shown in Å.

and the eigendisplacement vector $\xi_{\lambda i}$ of an atom *i* in a phonon mode λ at the zone center were calculated by diagonalizing dynamical matrices. The dynamical matrices were obtained as numerical first-order derivatives of the Hellmann-Feynman forces acting on atoms. The mode effective charge vector is given as

$$Z_{\lambda\alpha} = \sum_{i,\beta} Z_{i\alpha\beta}^* \xi_{\lambda i\beta} \frac{1}{\sqrt{M_i}},\tag{3}$$

where α and β denote Cartesian indices, M_i is the mass of an atom *i*, and $Z_{i\alpha\beta}^*$ is the Born effective charge tensor of an atom *i*. The $Z_{i\alpha\beta}^*$ were calculated by the Berry phase polarization method.^{43,44} The Z_{λ} is given as $Z_{\lambda}^2 = 1/3(Z_{\lambda x}^2 + Z_{\lambda y}^2 + Z_{\lambda z}^2)$.

III. MODEL STRUCTURES

Generated atomic structures of the amorphous models are shown in Fig. 1. Density, coordination number (CN) of Al and Hf, bond length distribution (BLD), and bond angle distribution (BAD) were analyzed for each amorphous model. CN of an Al atom of the amorphous models was defined as the number of O atoms around the Al atom, located within the Al atom centered sphere with a radius of 2.3 Å, and CN of a Hf atom of the models was defined similarly. The radius was determined from the first peak positions of Al-O and Hf-O BLDs of the models. The BLD was calculated in the same way as the radial distribution function (RDF), but BLD and BAD are calculated for first-principles optimized structures (not by taking the time average as usually done by MD calculation).

A. Amorphous Al₂O₃

Detailed results of the a-Al₄₈O₇₂ models have been reported previously in Ref. 17. CNs and densities are listed in Table I. In the a-Al₄₈O₇₂ models, four-coordinated Al atoms are predominant over five- and six-coordinated Al atoms; thus most of the Al atoms have smaller CN than Al atoms in α -Al₂O₃ crystal (CN=6). Calculated densities of the models are also smaller than values of α -Al₂O₃ crystal (4.0 g/cm³). Experimental densities of 3.05–3.40 g/cm³ and average Al

CN of 4.1–4.8 have been reported for the a-Al₂O₃ films,^{45–48} consistent with the calculated results.

Figure 2(a) shows the BLD of the a-Al₄₈O₇₂ (model A). At a long distance region over 4 Å, the total BLD of the model is flat and has a value of about 1, suggesting the absence of long-range structural order in the model structure. The total BLD of the model has a peak at 1.8 Å due to the Al-O bond, as shown by the partial BLD of the model. The total and partial BLDs show that the model has an amorphouslike structure, having a short-range order at the atomistic level. Partial BLD peaks of Al-Al and O-O are relatively broad, and the peak positions are at a longer bond distance than the Al-O BLD peaks. Calculated BLD peak positions are in good agreement with experimental RDF peak positions.^{23,46–48}

Figure 2(b) shows the BAD of O-Al-O of the a-Al₄₈O₇₂ (model A). The total BAD of O-Al-O lies in a wide range and shows that these models have several O-Al-O angles, different from that of Al₂O₃ crystals, which have fixed discrete bond angles. To clarify the CN dependence of bond angles, CN-dependent partial BADs are calculated for O-Al-O in the model. The partial BADs for four-coordinated

TABLE I. Densities (ρ) and coordination number (CN) distributions of Al and Hf of calculated models.

		CN	of Al	(%)	CN of Hf (%)				
Model	ho (g/cm ³)	4	5	6	5	6	7	8	
<i>a</i> -Al ₄₈ O ₇₂									
А	3.27	60.4	29.2	10.4					
В	3.22	54.2	43.7	2.1					
a-Hf ₈ Al ₃₂ O ₆₄									
А	4.93	43.8	53.1	3.1	62.5	37.5	0	0	
В	5.04	37.5	53.1	9.4	25.0	62.5	12.5	0	
С	5.20	37.5	53.1	9.4	12.5	75.0	12.5	0	
<i>a</i> -Hf ₃₂ O ₆₄									
А	10.20				6.2	59.4	31.3	3.1	
В	10.61				9.4	56.2	34.4	0	



FIG. 2. (Color online) (a) Total and partial bond length distributions (BLDs) and (b) total and partial bond angle distributions (BADs) of O-Al-O in a-Al₄₈O₇₂ (model A).

Al have a peak around 109.5°, which is the bond angle of the regular tetrahedral coordination, and those for sixcoordinated Al have a peak around 90°, which is the angle of regular octahedral coordination. The total BAD of O-Al-O has the maximum at about 100°, and this accords with the model having four-coordinated Al atoms predominantly.

The above results indicated that the amorphous models are composed of the distorted AlO_n (n=4-6) polyhedra (nstands for the coordination number). The connectivity between the neighboring AlO_n polyhedra can be seen in Fig. 1(a). The structures have polyhedra connected, sharing one, two, or three O atoms; i.e., corner, edge, or face shared polyhedra. In the a- $Al_{48}O_{72}$ models, the corner-shared polyhedra type is dominant (about 85%), and the face-shared type is quite few (less than 1%), as reported by the classical MD calculation.²³ The smaller CN and the weak connectivity between polyhedra account for the amorphous models having a lower density than Al_2O_3 crystals.

B. Amorphous HfO₂

Calculated densities of the a-Hf₃₂O₆₄ models (Table I) are between experimental densities of monoclinic hafnia (m-HfO₂) and cubic hafnia (c-HfO₂), which are 10.1 and 10.9 g/cm³, respectively. An experimental density of 9.68 g/cm³ has been reported for thick a-HfO₂ films.⁴⁹ We could not obtain a-HfO₂ models having such a low density in the present study. It has been shown by positron annihilation experiments that actual a-Hf_xAl_{1-x}O_y and a-Hf_xSi_{1-x}O_y films have large open spaces in their amorphous structures.^{50,51} Such large pore with a radius larger than 5 Å does not exist in our a-HfO₂ models, and this could be the reason for the



FIG. 3. (Color online) (a) Total and partial BLDs and (b) total and partial BADs of O-Hf-O in a-Hf₃₂O₆₄ (model A).

difference between theoretical and experimental densities of a-HfO₂. Ikeda *et al.* reported that a-HfO₂ and a-Hf_xSi_{1-x}O_y models with a large pore have been generated and investigated by the melt-and-quench first-principles MD simulations using the fixed unit cell during the MD simulations.²⁷

Hf atoms in the a-Hf₃₂O₆₄ models are coordinated by five to eight O atoms, and six- and seven-coordinated Hf atoms are predominant (Table I). The *m*-HfO₂ and *c*-HfO₂ crystals have seven- and eight-coordinated Hf atoms, respectively. The result shows that most Hf atoms in the *a*-Hf₃₂O₆₄ models have a smaller coordination number than Hf atoms in the crystals, as shown by previous first-principles MD studies.^{26,27}

Figure 3(a) shows BLD of the a-Hf₃₂O₆₄ (model A). The total and partial BLDs of a-Hf₃₂O₆₄ models show that the model has amorphouslike short- and long-range structural orders. The total BLD of the a-Hf₃₂O₆₄ model has a peak at 2.1 Å due to the Hf-O bond, as shown by the partial BLDs of the models. Partial BLD peaks of Hf-Hf and O-O are relatively broad, and the peak positions are at a longer bond distance than the Hf-O BLD peaks.

Figure 3(b) shows BAD of O-Hf-O for the a-Hf₃₂O₆₄ (model A). The total BAD of O-Hf-O for the model lies in a wide range and shows that these models have several O-Hf-O angles, different from that of HfO₂ crystals. CN-dependent partial BAD of O-Hf-O for the model shows that Hf atom having larger CNs has peak at smaller angles, as Al atoms in the a-Al₂O₃ model does [Fig. 2(b)]. The average CN of Hf atoms in the a-Hf₃₂O₆₄ models (CN=6.25-6.31) is larger than that of Al atoms in the a-Al₄₈O₇₂ models (CN = 4.48-4.50). This explains why the BAD peak position of O-Hf-O for the a-Hf₃₂O₆₄ model is smaller in angle than that of O-Al-O for the a-Al₄₈O₇₂ model.

The amorphous models are composed of the distorted HfO_n (n=5-8) polyhedra (n stands for the coordination



FIG. 4. (Color online) Total and partial BLDs of a-Hf₈Al₃₂O₆₄ models: (a) model A, (b) model B, and (c) model C. Shoulders at first peak of total BLD are shown by arrows.

number), and the connectivity between the neighboring HfO_n polyhedra can be seen in Fig. 1(b). The structures have polyhedra connected by sharing corner, edge, or face. In this view, the *c*-HfO₂ and *m*-HfO₂ crystals are composed of edge-shared HfO₈ polyhedra and corner- or edge-shared HfO₇ polyhedra, respectively. In the *a*-Hf₃₂O₆₄ models, the ratio of edge-shared polyhedra is also high (45% in model A and 41% in model B), relative to that of the *a*-Al₄₈O₇₂ models. In addition, there is an additional type of face-shared polyhedra (6% in model A and 9% in model B), which makes the system denser. The results account for the *a*-Hf₃₂O₆₄ models looking denser in structure compared with the *a*-Al₄₈O₇₂ models that are mainly composed of corner-shared polyhedra [Figs. 1(a) and 1(b)].

C. Amorphous Hf_{0.2}Al_{0.8}O_{1.6}

Calculated densities of the *a*-Hf₈Al₃₂O₆₄ models are in between those of *a*-Al₄₈O₇₂ and *a*-Hf₃₂O₆₄ models (Table I) and can approximately be given by the linear interpolation. To be precise, the *a*-Hf₈Al₃₂O₆₄ models are slightly denser by 4–12% than the interpolated values of 4.62–4.74 g/cm³. Although experimental densities have not been reported in our knowledge, it has been shown that there are large open spaces in *a*-Hf_{0.3}Al_{0.7}O_y films observed by positron annihilation experiments,⁵¹ as already mentioned.



FIG. 5. (Color online) Total BADs of O-Al-O and O-Hf-O in a-Hf₈Al₃₂O₆₄ models: (a) model A, (b) model B, and (c) model C.

The *a*-Hf₈Al₃₂O₆₄ models have five- to seven-coordinated Hf atoms. The CN distribution of Hf atoms is strongly model dependent because the models have only eight Hf atoms in the unit cell but, in all the models, five- and/or six-coordinated Hf atoms are dominant. The predominant Hf CN of the *a*-Hf₈Al₃₂O₆₄ models is smaller than the Hf CN of the *a*-Hf₈Al₃₂O₆₄ and HfO₂ crystals. The CN of Al atoms in the *a*-Hf₈Al₃₂O₆₄ models is from 4 to 6, similar to that of *a*-Al₄₈O₇₂ models. The predominant CN of Al atoms is 4 and 5 in both the *a*-Al₄₈O₇₂ and *a*-Hf₈Al₃₂O₆₄ models, but average CN of Al atoms is larger for the *a*-Hf₈Al₃₂O₆₄ models (CN=4.59–4.72). CN of most Al atoms is smaller than 6, which is the Al CN of α -Al₂O₃ crystal.

Figures 4(a)-4(c) show total and partial BLDs of the a-Hf₈Al₃₂O₆₄ models A, B, and C, respectively. The partial Al-O and Hf-O BLD peak positions of the models are almost the same as the Al-O BLD peak position of the a-Al₄₈O₇₂ models and the Hf-O BLD position of a-Hf₃₂O₆₄ models, respectively, and this explains why the first peak of the a-Hf₈Al₃₂O₆₄ model total BLD has a shoulder at the dip (the shoulder is due to the Hf-O BLD peak). Partial BLD peaks of O-O, Al-Al, Hf-Al (not shown), and Hf-Hf are relatively broad in all models, and the peak positions are at a longer bond distance than the Al-O and Hf-O BLD peaks. Note that Hf-Hf BLD peak positions of the *a*-Hf₈Al₃₂O₆₄ models are more scattered compared with those of the a-Hf₃₂O₆₄ models. The scattered peak positions of the a-Hf₈Al₃₂O₆₄ models are due to the models having a smaller number of Hf atoms in their unit cell. Experimental RDF of Hf-based oxide films has been observed by the grazing incidence x-ray diffraction methods, and the RDF of a-Hf_{0.3}Al_{0.7}O_y films shows an amorphous feature of the atomic structure.⁵² The peak positions of 2.14 and 3.48 Å have been reported,⁵² consistent with the calculated peak positions of Hf-O and Hf-Hf pair correlation, respectively.

Figures 5(a)-5(c) show total BADs of O-Al-O and O-Hf-O of the *a*-Hf₈Al₃₂O₆₄ models A, B, and C, respectively. The O-Al-O and O-Hf-O BADs are similar in distribution to the total O-Al-O BAD of the *a*-Al₂O₃ models and the total O-Hf-O BAD of the *a*-Hf₃₂O₆₄ models, respectively.

However, the O-Al-O BAD of the a-Hf₈Al₃₂O₆₄ models is slightly shifted toward the smaller angle, relative to that of the a-Al₂O₃ models, and the O-Hf-O BAD of the a-Hf₈Al₃₂O₆₄ models toward the larger angle, relative to that of the a-Hf₃₂O₆₄ models. The shift is due to the Al atom CN of the a-Hf₈Al₃₂O₆₄ models being higher in distribution than that of the a-Al₂O₃ models and the Hf atom CN of the a-Hf₈Al₃₂O₆₄ models being lower in distribution than that of the a-Hf₃₂O₆₄ models (Table I).

Detailed atomic structure of a-Hf_xAl_{1-x}O_y films has not been clarified yet, but it is practically known that the films show a strong tendency for phase separation into Al₂O₃ and HfO₂ during the CMOS annealing (about 1000 °C) if x of the film becomes high.^{4–7} Although the present study cannot discuss such phase separation at the mesoscopic level, calculated structures of the a-Hf₈Al₃₂O₆₄ models A, B, and C also have clustering Hf atoms connected by Hf-O-Hf bonds [Fig. 1(c)]. The *a*-Hf₈Al₃₂O₆₄ models have eight Hf atoms in a unit cell, and seven of the Hf atoms in model A are connected via the Hf-O-Hf bonds. Similarly, sets of four, two, and two Hf atoms are connected in model B, and sets of five and three Hf atoms cluster in model C. Model A (B) has the largest (smallest) size of Hf-O-Hf clusters, and this account for the difference in partial Hf-Hf BLD between the models at about 3-4.5 Å [Figs. 4(a) and 4(b)]. The results imply that a-Hf_xAl_{1-x}O_y tend to phase separate in an atomic scale, even if their x is 0.2 and they look like homogeneous films in a mesoscopic scale. The clustering of the Hf atoms accounts for the observed Hf-Hf RDF high peak at 3.48 Å in the a-Hf_{0.3}Al_{0.7}O_y film.⁵² It has been reported that the x-ray diffraction spectra of the a-Hf_xAl_{1-x}O_y films show crystalline HfO₂ peaks after the 1000 °C annealing even for x=0.28.⁸ Note that the average CN of the Hf in the a-Hf₈Al₃₂O₆₄ models (CN=5.38-6.00) is much lower than that in the monoclinic (CN=7), cubic (CN=8), and orthorhombic crystal phases, and that all the Hf atoms also have the Hf-O-Al connections.

We used these model structures in an attempt to study dielectric responses of $a-Hf_xAl_{1-x}O_y$ with x=0, 0.2, and 1.

IV. RESULTS FOR DIELECTRIC CONSTANTS

A. Dielectric constant

Figure 6(a) shows calculated ε of several a-Hf_xAl_{1-x}O_y models, a-Al₄₈O₇₂ models A and B (x=0) investigated in our previous study,¹⁷ and those investigated in the present study: a-Hf₈Al₃₂O₆₄ models A, B, and C (x=0.2) and a-Hf₃₂O₆₄ models A and B (x=1). The values are listed in Table II.

Calculated ε increase with increasing *x*, and the trend is in accordance with experimental results.^{4,6–9} The ε values for the *a*-Al₄₈O₇₂ and *a*-Hf₃₂O₆₄ models are in the reported experimental ranges of Al₂O₃ films^{4,6,8,9,53,54} (8–11) and HfO₂ films (15–25),^{4,6–9,12,13} respectively. Recently, Tomida *et al.* have studied the effects of structural phase transformations on the ε of HfO₂ films by doping small amount of Si atoms.¹² They show that the ε of HfO₂ films significantly depends on the film structures, and the observed ε are about 15 and 27 for the films crystallized to monoclinic and tetrag-



FIG. 6. (a) Dielectric constants (ε) and (b) electronic and lattice polarization contributions to the ε (ε^{ele} and ε^{lat}) of a-Al₄₈O₇₂, a-Hf₈Al₃₂O₆₄, and a-Hf₃₂O₆₄ models, which have Hf contents (x) of 0, 0.2, and 1, respectively. Broken lines are for linear interpolation.

onal (or cubiclike) phases, respectively, and about 20 for the amorphous films.¹² The experimental result shows good agreement with the present and reported ε values of the amorphous and the crystalline HfO2, 15,26,38-40 as well as results for Al_2O_3 .¹⁷ Calculated ε of the *a*-Hf₈Al₃₂O₆₄ models are in between the a-Al₄₈O₇₂ and a-Hf₃₂O₆₄ values, and can be roughly estimated from these values by a linear interpolation. It has been experimentally reported that ε of $Hf_{x}Al_{1-x}O_{y}$ films increases almost linearly with increasing x in the range from 0 to about 0.5,^{4,6,7,9} although the correlation between ε of $Hf_xSi_{1-x}O_v$ films and the x shows significant variety depending on the film preparation conditions.¹³ Compared with the experimental values at a low xrange,^{4,6,7,9} calculated degrees of the increase of the ε from x=0 to x=0.2 are reasonable, though the calculated ε for these amorphous models differ even when the models have the same x.

Figure 6(b) shows calculated ε^{ele} and ε^{lat} against *x*. Both the ε^{ele} and ε^{lat} of the models increase with increasing *x*, and the increase of the ε^{lat} is more significant. The results show that the experimentally observed increase of ε of Hf_xAl_{1-x}O_y

TABLE II. Dielectric constants ($\varepsilon = \varepsilon^{\text{ele}} + \varepsilon^{\text{lat}}$) with electronic and lattice polarization contributions (ε^{ele} and ε^{lat}), and electronic band gap (E_e) of calculated models.

Model	ε	ϵ^{ele}	$arepsilon^{ ext{lat}}$	E_g (eV)						
<i>a</i> -Al ₄₈ O ₇₂										
А	10.48	3.11	7.37	3.77						
В	8.85	3.06	5.79	3.56						
a-Hf ₈ Al ₃₂ O ₆₄										
А	12.14	3.55	8.59	3.57						
В	11.01	3.55	7.46	3.01						
С	14.07	3.61	10.46	2.93						
<i>a</i> -Hf ₃₂ O ₆₄										
А	18.99	5.21	13.78	3.05						
В	22.26	5.38	16.88	2.82						



FIG. 7. Electronic density of states (*el*-DOS) of (a) a-Al₄₈O₇₂, (b) a-Hf₈Al₃₂O₆₄, and (c) a-Hf₃₂O₆₄ models. The top of the valence band is taken at the energy origin for each of the models.

with increasing x is mainly due to the increase of ε^{lat} . Zhao *et al.* have investigated structural and dielectric properties of a-ZrO₂ and a-HfO₂ by the first-principles method,^{24–26} and ε^{lat} of 16.8 for a-HfO₂ has been reported,²⁶ consistent with the present results.

In the following, we analyzed the ε^{ele} and ε^{lat} of the amorphous models in relation to their electronic band and lattice vibration structures of the models, respectively.

B. Electronic dielectric constant

Figures 7(a)–7(c) show electronic density of states (*el*-DOS) of the *a*-Al₄₈O₇₂,¹⁷ *a*-Hf₈Al₃₂O₆₄, and *a*-Hf₃₂O₆₄ models, respectively, calculated by using the $4 \times 4 \times 4$ **k** mesh. Valence bands of all the models in the energy range from –20 to –15 eV are mainly composed of *s* orbitals of O atoms and those in the range from –8 to 0 eV are of *p* orbitals of O atoms. All the models are insulators without midgap levels, contrary to Hf-based oxides with O vacancies.^{14,15,56} On the other hand, conduction-band edge features of the models differ significantly, depending on whether the models have Hf atoms or not. Each of the *a*-Al₄₈O₇₂ models without Hf atoms has a low *el*-DOS at the band edge, while each of the *a*-Hf₈Al₃₂O₆₄ and *a*-Hf₃₂O₆₄ models with Hf atoms has a high *el*-DOS at the band edge. The differences are due to the

fact that the conduction band edge states of the a-Al₄₈O₇₂ models are delocalized,¹⁷ whereas those of the Hf-containing models have the Hf *d* orbital character and are localized. The *el*-DOS near the conduction-band edge becomes high with increasing *x* due to the localized Hf *d* characters.

Calculated electronic band gaps of the models are listed in Table II. Calculated band gaps of the a-Al₄₈O₇₂ and a-Hf₃₂O₆₄ models are smaller than experimental band gaps of a-Al₂O₃ films^{10,11,55} (5–7 eV) and a-HfO₂ films (5–6 eV),^{10,11,56} respectively. This is due to the DFT-LDA calculation, which usually underestimates experimental band gaps. Note that the experimental values depend on film structure, thickness, and other experimental conditions. It has been reported for a $Hf_rAl_{1-r}O_v$ film that the optical band gaps decrease linearly from Al_2O_3 (6.25 eV) to HfO₂ (5.56 eV) values with increasing HfO₂ mole fraction.¹⁰ On the other hand, it has also been reported that the band gap decreases from Al₂O₃ (about 6.0 eV) to HfO₂ (5.6 eV) values with nonlinear dependence of the mole fraction by electron photoemission experiments, indicating less contribution of Hf at the conduction-band edge.¹¹ Within the DFT-LDA, calculated band gaps of the a-Hf32O64 models are also smaller than those of the a-Al₄₈O₇₂ models. Assuming that the underestimation is similar between the calculations, we expect that the band gap of $Hf_xAl_{1-x}O_y$ tends to be reduced with increasing x. Note that, to be precise, calculated band gaps of the a-Hf₈Al₃₂O₆₄ models depend on the lowest energy position of the localized Hf d state as seen in Fig. 7(b).

The above results indicate that electronic transitions from the valence O p bands to the conduction Hf d bands mainly contribute to the ε^{ele} of the models having Hf atoms. The increase of the ε^{ele} with increasing x could be attributed to these transitions, which have a lower transition energy. In fact, the imaginary part of the calculated dielectric function of each of the Hf-containing model has a higher peak due to the transitions from O p bands to the conduction-band edge at a lower energy.⁵⁷

C. Lattice dielectric constant

Figure 8 shows average Born effective charges of Al, Hf, and O atoms of the a-Al₄₈O₇₂,¹⁷ a-Hf₈Al₃₂O₆₄, and a-Hf₃₂O₆₄ models against x. The charges were obtained by taking the average of the Born effective charge tensors of atoms of each species and by calculating the third of the trace of the averaged tensor. The charges of the Hf and Al species increase in magnitude with increasing x, and the charge of O atoms linearly decreases in magnitude as x increases. The charges for each atomic species are similar between the models at the same x. To clarify the reason for the charge magnitude enhancement, we investigated correlations between the Born effective charge tensors of atoms and the atomic environment, and found that Al and O atoms in Al-O-Hf structures have the Born effective charges larger in magnitude than Al and O atoms in other Al-O-Al structures, respectively. The charge magnitude enhancement thus appears to be due to the increase of the number of the Al-O-Hf structures by Hf doping.

Figure 9 shows the calculated zone-center phonon density of states (*ph*-DOS) of the a-Al₄₈O₇₂ model A,¹⁷



FIG. 8. Born effective charges of (a) Al and Hf, and (b) O atoms in a-Al₄₈O₇₂, a-Hf₈Al₃₂O₆₄, and a-Hf₃₂O₆₄ models, which have Hf contents (*x*) of 0, 0.2, and 1, respectively. The values are averaged over atoms in each atomic species and three diagonal components. The broken line in (b) is for linear interpolation.

a-Hf₈Al₃₂O₆₄ model A, and *a*-Hf₃₂O₆₄ model A. Total (upper panels) and partial (lower panels) *ph*-DOS are calculated as $\Sigma_{\lambda}\delta(\omega_{\lambda}-\omega)$ and $\Sigma_{i \in \tau,\lambda}|\xi_{\lambda i}|^2\delta(\omega_{\lambda}-\omega)$ for each atomic species τ , respectively.²⁴ The *ph*-DOS of the *a*-Al₄₈O₇₂ model dis-



FIG. 9. (Color online) Histogram plots of zone-center phonon density of states (*ph*-DOS) of (a) a-Al₄₈O₇₂ (model A), (b) a-Hf₈Al₃₂O₆₄ (model A), and (c) a-Hf₃₂O₆₄ (model A). Histogram width is 20 cm⁻¹. Upper and lower panels show total and atom-decomposed *ph*-DOS, respectively.



FIG. 10. Infrared active phonon density of states (IR-*ph*-DOS, see text) of (a) a-Al₄₈O₇₂, (b) a-Hf₈Al₃₂O₆₄, and (c) a-Hf₃₂O₆₄. Histogram width is 20 cm⁻¹.

tributes in a wide frequency range and is from both Al and O atom vibration state contributions. The *ph*-DOS of the *a*-Hf₃₂O₆₄ model distributes in a lower frequency range compared with that of the *a*-Al₄₈O₇₂. Vibration frequency distributions of Hf and O atoms in the *a*-Hf₃₂O₆₄ model are separated; the almost Hf atom vibration frequencies are lower and the almost O atom vibration frequencies are higher than about 300 cm⁻¹. The *ph*-DOS of the *a*-Hf₈Al₃₂O₆₄ model also distributes in a low-frequency range, and the lowfrequency distribution less than 300 cm⁻¹ is from Hf atom vibrations. These results indicate that the distribution of *ph*-DOS of *a*-Hf_xAl_{1-x}O_y is lowered as the *x* is increased, and this lowering causes the enhancement of ε^{lat} .

To clarify phonon modes causing the ε^{lat} enhancement, infrared active *ph*-DOS (IR-*ph*-DOS), given as $(4\pi e^2/V)\Sigma_{\lambda}(3Z_{\lambda}^2/\omega_{\lambda}^2)\delta(\omega_{\lambda}-\omega)$,²⁴ were calculated. By the definition, the intensity of IR-*ph*-DOS is nonzero for infrared active modes, and the integration of IR-*ph*-DOS gives three times the lattice dielectric constant (sum of the diagonal components, $3\varepsilon^{\text{lat}} = \varepsilon_{xx}^{\text{lat}} + \varepsilon_{yy}^{\text{lat}} + \varepsilon_{zz}^{\text{lat}}$). Figure 10 shows IR-



FIG. 11. (Color online) Examples of low-frequency phonon modes largely contributing to high lattice dielectric constant: (a) mode of a-Al₄₈O₇₂ (model A), (b) mode of a-Hf₃₂O₆₄ (model A), and (c) mode of a-Hf₈Al₃₂O₆₄ (model C). Arrows denote eigendisplacement vectors of the mode. Schematic pictures in lower part show rough sketches of the modes and polyhedra structures and positions of atoms largely vibrating in the modes.

ph-DOS of all the models of a-Al₄₈O₇₂, a-Hf₈Al₃₂O₆₄, and a-Hf₃₂O₆₄, along with ε^{lat} of the models. All the models have high peaks at frequencies less than 200 cm⁻¹, and the highest peak intensity of the models correlates with the ε^{lat} of the models. In the case of the a-Hf₈Al₃₂O₆₄ models, the intensity of low-frequency peaks significantly changes, depending on the models.

Atomic vibrations of the amorphous models at frequencies less than 200 cm-1 are analyzed to clarify atomic motions significantly contributing to ε^{lat} of the models. Figure 11 shows eigendisplacement vectors $\xi_{\lambda i}$ of phonon modes having high $(Z_{\lambda}/\omega_{\lambda})^2$ values. Lattice vibrations of a solid are composed of elastic waves, and the low-frequency vibrations are composed of elastic waves having a long wavelength. Phonon modes shown in Fig. 11 are such modes. The $a-Al_{48}O_{72}$ and the $a-Hf_{32}O_{64}$ consist of hard domains, for example, which are mainly composed of edge- and faceshared polyhedra and are connected with each other by corner-shared polyhedra. The phonon modes of these models include the vibration of the domains [see Figs. 11(a) and 11(b)]. In the case of the a-Hf₈Al₃₂O₆₄ model, the phonon modes include distance stretching vibrations between HfO₂ domains [Fig. 11(c)]. Other low-frequency modes of the model include large displacements of atoms in some distorted AIO_n or HfO_n polyhedra. We previously found in the a-Al₂O₃ models that atoms in distorted polyhedra, such as polyhedra having planar structure, largely contribute to ε^{lat} via low-frequency modes.¹⁷ Atoms in such planar polyhedra have weakly connected to neighboring atoms, and the potential around them is shallow in the direction perpendicular to the plane. Low-frequency modes of the a-Hf₈Al₃₂O₆₄ show that ε^{lat} of a-Hf_xAl_{1-x}O_y is enhanced by elastic phonon

modes as well as phonon modes localized at distorted polyhedra.

V. SUMMARY

We have calculated the atomistic and electronic structures of stoichiometric a-Hf_xAl_{1-x}O_y [y=(3+x)/2] models with the Hf content x of 0, 0.2, and 1, and investigated the dielectric response of the models, taking into account the electronic as well as lattice vibrational contributions to the response, by first principles. It was found that the models are phase separated to Al₂O₃ and HfO₂ domains at the atomistic level, and are insulators. Calculated dielectric constants were consistent with experimental results, and the dielectric constants increased with increasing x from 0 (the a-Al₂O₃ case) to 1 (the a-HfO₂ case). The lattice polarization contribution to dielectric constant was dominant over the electronic one, and low-frequency phonon modes with frequencies less than 200 cm⁻¹ largely contribute to the large lattice polarization contribution. Inter-HfO₂ domain vibrations as well as vibrations of atoms in distorted AlO_n and HfO_n polyhedra significantly contribute to the higher lattice dielectric constant of the a-Hf_xAl_{1-x}O_y models through these low-frequency phonon modes.

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